CLAIMS

1. A deposit removal method comprising removing a selenium-containing deposit adhering to at least one of an inner surface of a chamber or an inner surface of piping connected to the chamber by reacting the deposit with a cleaning gas consisting of a hydrogen-containing compound gas, or consisting of a hydrogen-containing compound gas and an inert gas~~containing a hydrogen-containing compound gas.~~,

wherein the cleaning gas is a gas of a compound including a hydrogen atom, and not including selenium and halogen atoms, and

wherein the cleaning gas is brought into contact with the deposit under conditions of a temperature of from 350°C to 800°C.

2. The deposit removal method according to claim 1, wherein the cleaning gas is brought into contact with the deposit under conditions of a temperature of from ~~20~~350°C to 800°C and a pressure of from 20 Pa to 101 kPa.

3. The deposit removal method according to claim 1 or 2, wherein the hydrogen-containing compound gas is at least one selected from a group consisting of hydrogen gas, hydrocarbon gas, and ammonia gas.

4. The deposit removal method according to claim 1 or 2, wherein the hydrogen-containing compound gas is hydrogen gas.

5. A film deposition method comprising:

a passivation step of supplying a passivation gas containing a selenium-containing compound gas to a chamber housing a substrate and reacting the substrate with the passivation gas to deposit a passivation film on a surface of the substrate; and

a deposit removal step of, after performing the passivation step, removing a selenium-containing deposit adhering to at least one of an inner surface of the chamber or an inner surface of piping connected to the chamber,

wherein the deposit removal step is performed by the deposit removal method according to any one of claims 1 to 4.

6. The film deposition method according to claim 5, wherein the selenium-containing compound gas is hydrogen selenide gas.